



SEMiX® 2s

Rectifier Diode Module SEMiX302KD16s

Features

Terminal height 17 mm
Chips soldered directly to isolated substrate

Typical Applications*

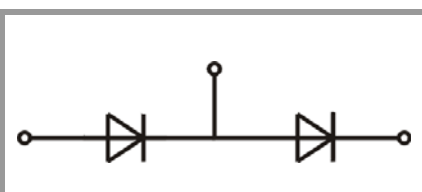
- Input Bridge Rectifier for AC/DC motor control
- Power supply

Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Recitifier Diode				
I _{FAV}	sin. 180°	T _c = 85 °C	300	A
		T _c = 100 °C	240	A
I _{FSM}	10 ms	T _j = 25 °C	8500	A
		T _j = 130 °C	7500	A
i ² t	10 ms	T _j = 25 °C	361000	A ² s
		T _j = 130 °C	281000	A ² s
V _{RSM}			1700	V
V _{RRM}			1600	V
T _j			-40 ... 130	°C
Module				
T _{stg}			-40 ... 125	°C
V _{isol}	AC sinus 50Hz	1 min	4000	V
		1 s	4800	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
Diode					
V_F	$T_j = 25\text{ °C}$, $I_F = 900\text{ A}$			1.6	V
$V_{(TO)}$	$T_j = 130\text{ °C}$			0.85	V
r_T	$T_j = 130\text{ °C}$			1.1	mΩ
I_{RD}	$T_j = 130\text{ °C}$, $V_{RD} = V_{RRM}$			15	mA
$R_{th(j-c)}$					K/W
					K/W
$R_{th(j-c)}$	sin. 180			0.091	K/W
					K/W
Module					
$R_{th(c-s)}$	per chip				K/W
	per module		0.045		K/W
M_s	to heat sink (M5)	3		5	Nm
M_t	to terminals (M6)	2.5		5	Nm
a				5 * 9,81	m/s ²
w			250		g



KD

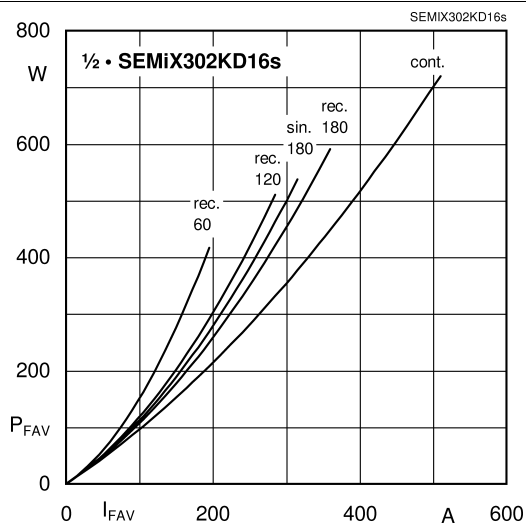


Fig. 1L: Power dissipation per thyristor/diode vs. on-state current

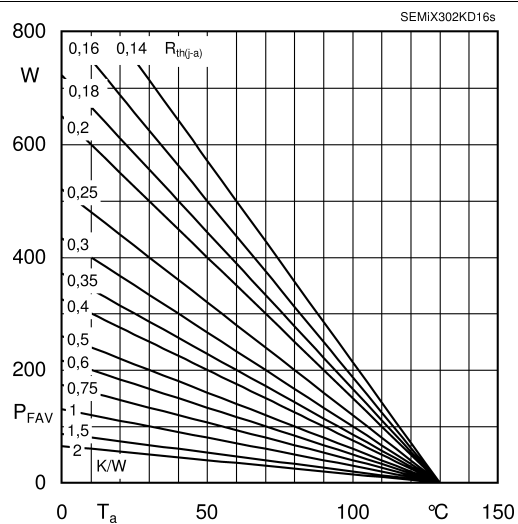


Fig. 1R: Power dissipation per thyristor/diode vs. ambient temperature

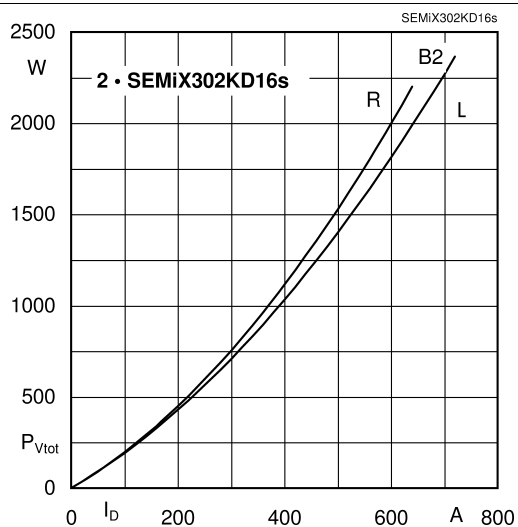


Fig. 3L: Power dissipation of two modules vs. direct current

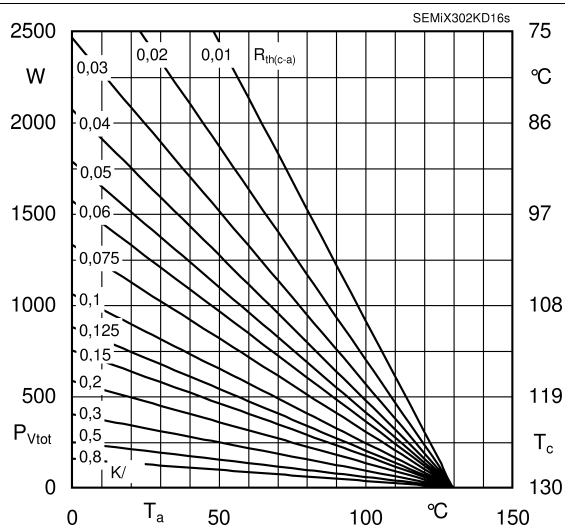


Fig. 3R: Power dissipation of two modules vs. case temperature

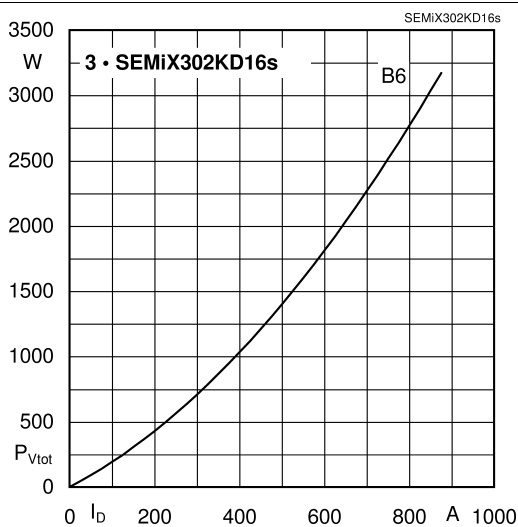


Fig. 4L: Power dissipation of three modules vs. direct current

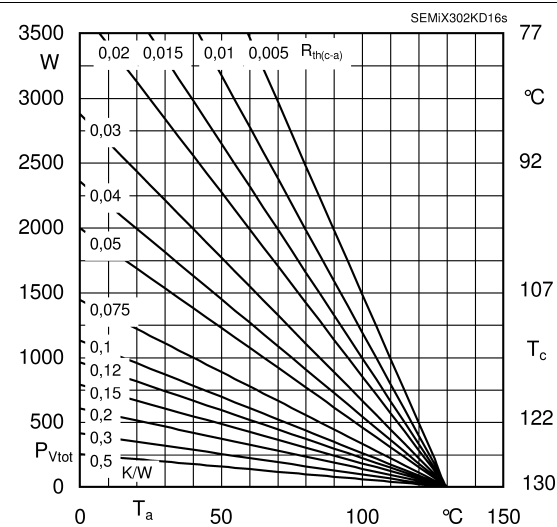


Fig. 4R: Power dissipation of three modules vs. case temperature

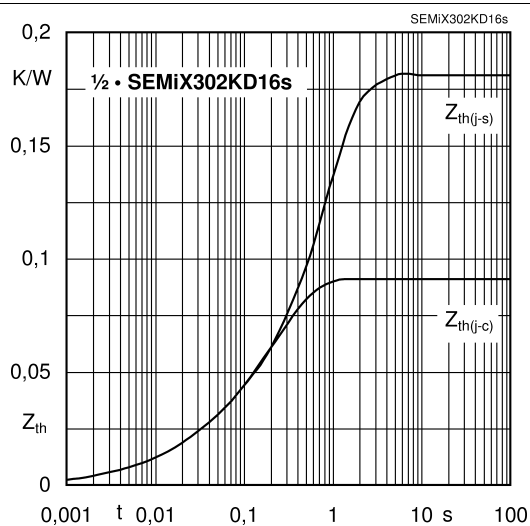


Fig. 6: Transient thermal impedance vs. time

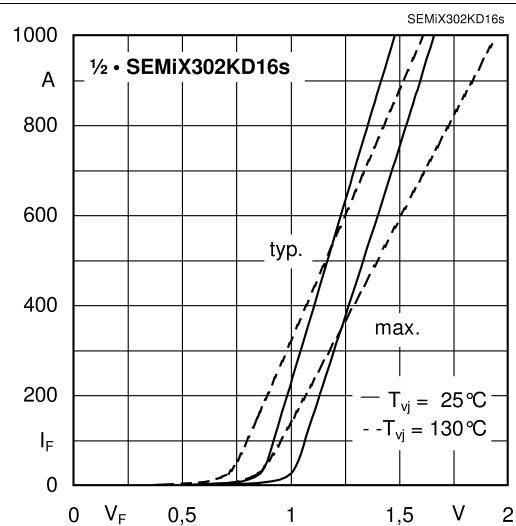


Fig. 7: On-state characteristics

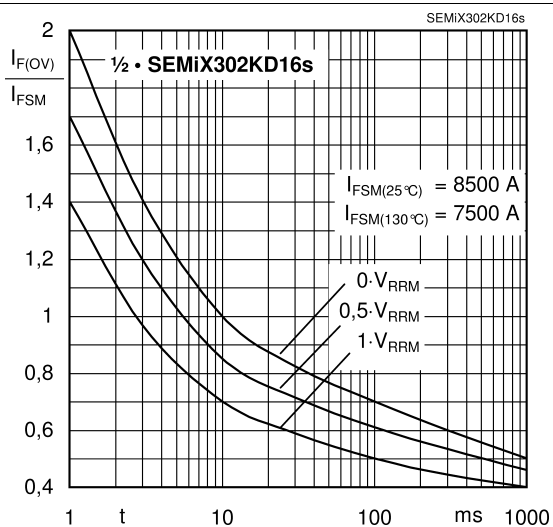
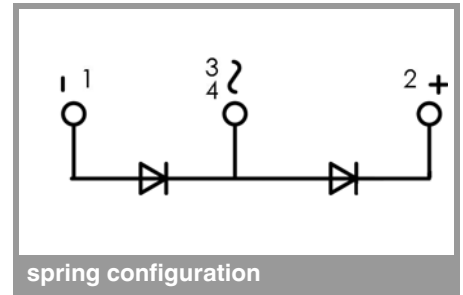
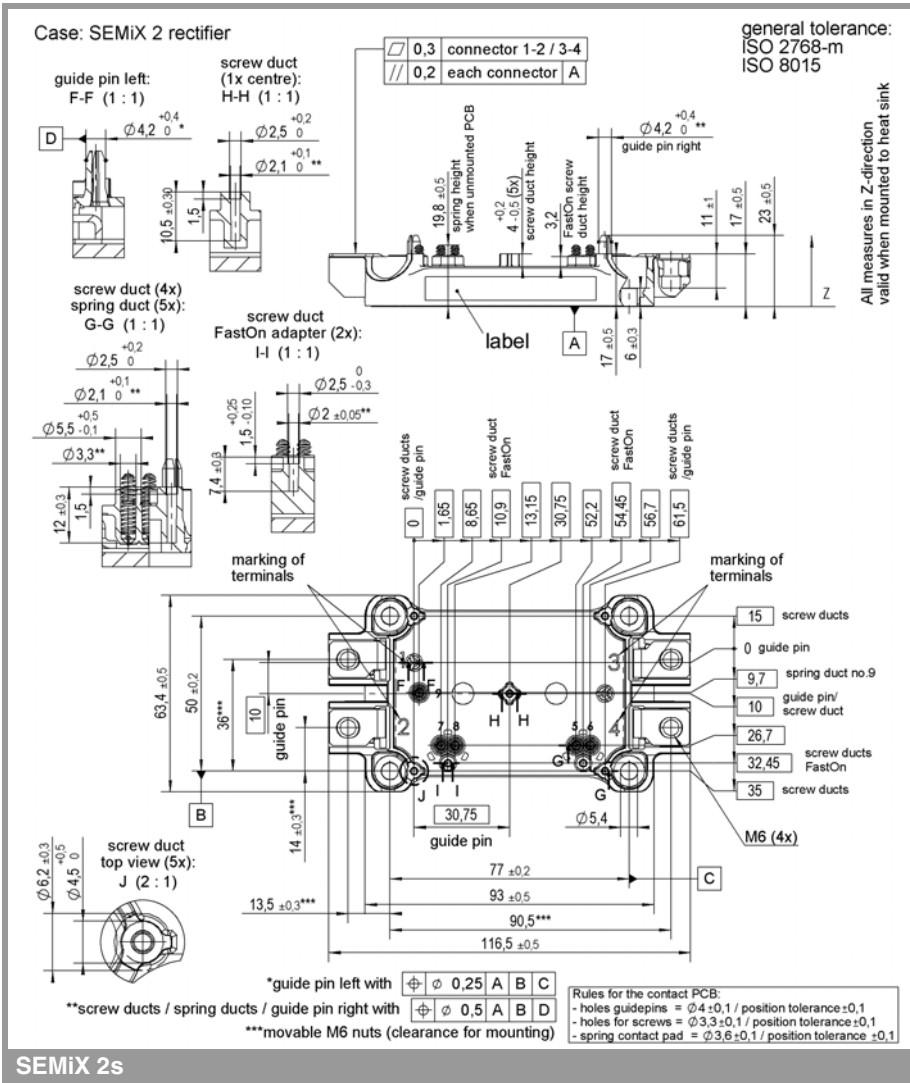


Fig. 8: Surge overload current vs. time



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.